

Hur does not disclose a method of fabricating a semiconductor device including, inter alia, a step of cutting a tape to obtain substrates and a step of providing a plurality of external terminals on each of the substrates, as recited in claim 1.

Instead, according to the method of Hur, external terminals 3B are disposed over a mold cavity 10, and then the leads 3B are provided to a reel-to-reel type tape 11. See column 3, lines 28-48, and Figs. 4A and 4B of Hur. Thus, in contrast to the method of claim 1, the external terminals of Hur are not provided on a substrate cut from a tape.

Providing a plurality of external terminals on a substrate cut from the tape provides significant advantages. For example, as discussed on page 15, lines 4-6 of the present specification, providing a plurality of external terminals on a substrate cut from the tape diminishes disposal losses if a faulty sample occurs in the step of providing external terminals.

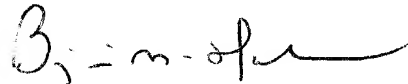
For at least these reasons, it is respectfully submitted that claim 1 is patentable over the applied references. The dependent claims are likewise patentable over the applied references for at least the reasons discussed as well as for the additional features they recite. Applicant respectfully requests that the rejection under 35 U.S.C. §102 be withdrawn.

II. Conclusion

In view of the foregoing, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe anything further is desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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Attachments:
Appendix
Terminal Disclaimer

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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APPENDIX

Changes to Claims:

The following are marked-up versions of the amended claims:

1. (Amended) A method of fabricating a semiconductor device comprising:
~~a step (a) of attaching a plurality of semiconductor chips to a tape;~~
~~a step (b) of cutting the tape to obtain substrates; and~~
~~a step (c) of providing a plurality of external terminals on a each of the~~
~~substrate substrates cut from the tape in the step (b),~~
wherein the steps (a) and (b) are carried out in a reel-to-reel transport system.
2. (Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:
~~a step of adhering~~attaching a reinforcing member to the tape in positions corresponding to each of the semiconductor chips, before the step (b).
7. (Amended) The method of fabricating a semiconductor device as defined in claim 5, further comprising:
~~wherein cutting the substrate cut from the tape is further cut into the~~
semiconductor chips after the step (c).
8. (Amended) The method of fabricating a semiconductor device as defined in claim 6, further comprising:
~~wherein cutting the substrate cut from the tape is further cut into the~~
semiconductor chips after the step (c).
9. (Amended) The method of fabricating a semiconductor device as defined in claim 1,

wherein a plurality of device holes are formed in the tape, and leads are formed ~~above on~~ the tape, whose ~~which~~ end portions project into the respective device holes; and

wherein each of the semiconductor chips is disposed within a respective one of the device holes, and the electrodes of the semiconductor chips and the leads are bonded in the step (a).

11. (Amended) The method of fabricating a semiconductor device as defined in claim 10,

wherein by means of an anisotropic conductive material, the electrodes of the semiconductor chips are lead formed ~~above on~~ the tape are electrically connected in the step (a).

13. (Amended) The method of fabricating a semiconductor device as defined in claim 12,

wherein the electrodes of the semiconductor chips and leads formed ~~above on~~ the tape are electrically connected by means of wires in the step (a).

14. (Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

~~a step of adhering~~ attaching a heat radiating member to each of the semiconductor chips.

15. (Amended) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

~~a step of adhering~~ attaching a heat radiating member to each of the semiconductor chips.

16. (Amended) The method of fabricating a semiconductor device as defined in claim ~~14~~ 1, further comprising:

~~wherein the step of adhering attaching the heat radiating member is carried out~~
before the step (b), with a reel-to-reel transport system.

17. (Amended) The method of fabricating a semiconductor device as defined in
claim ~~152~~, further comprising:

~~wherein the step of adhering attaching the heat radiating member is carried out~~
before the step (b), with a reel-to-reel transport system.